



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-01-24
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ACST1635-8FP	7TUI*A6C168H	A	3068	2017-01-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.15-4.5	3	Through-hole	
Comment	TO 220 ISOL FULL PACK 0.5 AB			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7TUI* A6C168H					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	6.889	mg	supplier	die	Silicon (Si)	7440-21-3		6.483	mg	941065	3412
				supplier	metallization	Aluminium (Al)	7429-90-5		0.107	mg	15532	56
				supplier	Passivation	Silicon Oxide	7631-86-9		0.035	mg	5083	18
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.066	mg	9580	35
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.066	mg	9580	35
				supplier	back side metallization	Gold (Au)	7440-57-5		0.066	mg	9580	35
Leadframe	Copper & its alloys	605.983	mg	supplier	alloy	Copper (Cu)	7440-50-8		604.468	mg	997500	318141
				supplier	alloy	Iron (Fe)	7439-89-6		0.278	mg	459	146
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.508	mg	838	267
				supplier	metallization	Nickel (Ni)	7440-02-0		0.674	mg	1112	355
				supplier	metallization	Phosphorus (P)	12185-10-3		0.055	mg	91	29
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	7.689	mg	955037	4047
Soft solder	Solder	8.051	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.201	mg	24966	106
				supplier	solder	Tin (Sn)	7440-31-5		0.161	mg	19997	85
				supplier	wire	Aluminium (Al)	7429-90-5		4.412	mg	1000000	2322
Bonding wires	Other inorganic materials	4.412	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.412	mg	1000000	2322
				supplier	die	Quartz	14808-60-7		888.159	mg	700000	467452
				supplier	mold compound	Silica, vitreous	60676-86-0		95.160	mg	75000	50084
				supplier	mold compound	Epoxy resin	25068-38-6		177.632	mg	140000	93491
				supplier	mold compound	phenol resin	29690-82-2		88.816	mg	70000	46745
				supplier	mold compound	metal hydroxide	21645-51-2		12.688	mg	10000	6678
Encapsulation	Other Organic Materials	1268.799	mg	supplier	mold compound	carbon black	1333-86-4		6.344	mg	5000	3339
				supplier	mold compound	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087
				supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087
Connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087